BOND® 3673

Non-conductive Die Attach Adhesive for LED(VS. OE8110)

產品特色	產品優勢
單液型	無需攪拌 (容易加工)
在光照及高溫下不易黃變	膠不易坍塌及擴散
可作業時間長	操作性佳
中等黏度	適用製程如 pin transfer 及 dispensing 等.

產品描述:

Bond ®3673為單液型, 白色膏狀Hybrid Chemistry接著劑 (為複合材料,非Epoxy),
可適用于LED薄型晶片快速點膠或沾膠制程，
固化後具有導熱特性，能降低LED晶片熱量累積，並能承受無鉛制程的能力，可應用于多種不同
薄型晶片/支架/底座進行黏著。

應用領域:

Bond ®3673 為**Chip LED, GaN LED chip,LED lamp bonding** 等應用之黏晶膠, 可用於 pin transfer and dispensing等製程.

- 可適用於快速點膠或沾膠制程之單液型環氧接著劑
- 良好接著強度與優異操作性
- 能承受無鉛制程高溫攝氏 260 度要求

UNCURED PROPERTIES		TEST DESCRIPTION
外觀	白色膏狀物	目視
黏度 @ 25℃	20000cps	Brookfield RVDV-II@ 5rpm
搖變指數 @ 25℃	2.5	Brookfield RVDV-II@ 5rpm Visc. @ 0.5rpm/Visc @ 5rpm
細度	< 10μm	
含水率	< 0.7 %	25℃/24hours
操作時間@ 25℃	24hrs	黏度增加 25%@ 5rpm
保存時間@ -20℃	6months	
折射率 Refractive Index	1.48	
CURE CONDITION		**TEST DESCRIPTION**
標準硬化條件(烘箱烘烤)		熱風烘箱升溫至 150℃+ 90min @150℃
MECHANICAL PROPERTIES-POST CURE		**TEST DESCRIPTION**
Die Shear Strength @ 25℃	>12 Kg/die	2mm×2mm (80mil×80 mil) 銀支架
PHYSIOCHEMICAL PROPERTIES-POST CURE		**TEST DESCRIPTION**
Weight Loss on Cure@ 200℃	<1 %	Thermo gravimetric Analysis

The figures shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

線膨張係数（25-150℃） Cohesion of Thermal Expansion	130 ppm/°C	Coefficient of Thermal Expansion
導熱係數	1.2W/mK	Hot disk
Glass Transition Temperature	155℃	DSC

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. DO NOT open the container before contents reach 25°C temperature.
   Any moisture that collects on the thawed container should be removed prior to opening the container.
4. DO NOT re-freeze. Once thawed to -20°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

1. Thawed adhesive should be immediately placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the product's recommended work life.
4. Apply enough adhesive to achieve a 25 to 50 μm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
5. Alternate dispense amounts may be used depending on the application requirements.
6. Star or crossed shaped dispense patterns will yield fewer bondline voids that the matrix style of dispense pattern.

APPLICATION GUIDELINES

UNPACKING

Transfer the syringes from the dry ice to a -20°C freezer without ANY delays. Freeze-thaw voids will form in the syringes if the syringes are repeatedly thawed and refrozen.

STORAGE

This product must be stored at -20°C. The shelf life of the material is only valid when the material has been stored at the specified storage condition. Incorrect storage conditions will degrade the performance of the material in both handling (e.g. dispensing or screen printing) and final cured properties.

THAWING

Allow the container to reach room temperature before use. After removing from the freezer, set the syringes to stand vertically while thawing.

DO NOT open the container before contents reach ambient temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.